

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application. Please add new claims 12 and 13, as follows:

1. (Original) A method for manufacturing a wafer-level package, comprising:
providing a first wafer and a second wafer;
removing a portion from the first wafer to form a gasket;
forming a pad on the second wafer, the pad substantially matching the gasket;
interposing bonding material between the gasket and the pad; and
bonding the gasket to the pad with the bonding material to create a
hermetically sealed environment between the first and second wafers.
2. (Original) The method of claim 1 wherein the first wafer consists of silicon.
3. (Original) The method of claim 2 wherein the gasket is no more than 20 um wide.
4. (Original) The method of claim 3 wherein the gasket is no more than 10 um wide.
5. (Original) The method of claim 3 wherein interposing bonding material includes depositing bonding material on the gasket.
6. (Original) The method of claim 3 wherein interposing bonding material includes depositing bonding material on the pad.
7. (Original) The method of claim 3 wherein the bonding material includes conductive bonding material.
8. (Original) The method of claim 7 wherein the conductive bonding material is a metal selected from the group consisting of gold, gold-tin, tin-lead, and palladium-tin.

9. (Original) The method of claim 3 wherein the bonding material includes non-conductive bonding material.
10. (Original) The method of claim 9 wherein the non-conductive bonding material is a material selected from the group consisting of polyimide, B-staged bisbenzocyclobutene (BCB), and glass.
11. (Original) The method of claim 10 wherein interposing an adhesion promoter between the gasket and the pad occurs after interposing bonding material.
12. (New) A method for manufacturing a wafer-level package, comprising:
 - providing a first wafer and a second wafer;
 - forming a pad on the second wafer, the pad substantially matching a gasket of the first wafer;
 - interposing bonding material between the gasket and the pad; and
 - bonding the gasket to the pad with the bonding material to create a hermetically sealed environment between the first and second wafers.
13. (New) A method for manufacturing a wafer-level package, comprising:
 - providing a first wafer and a second wafer;
 - removing a portion from the first wafer to form a gasket; and
 - bonding the gasket to the second wafer to create a hermetically sealed environment between the first and second wafers.